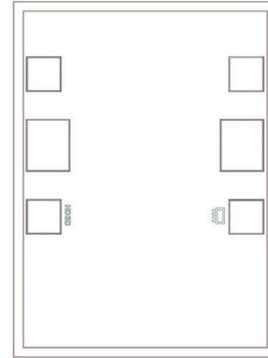


Product Features

- 3.0 dB Slope
- Wide Bandwidth, DC-20 GHz
- Excellent Return Loss, 20 dB typ.

Typical Applications

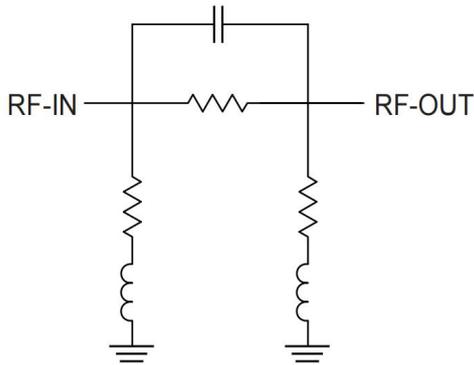
- Fixed Satellite
- Mobile
- Radio location
- Space research



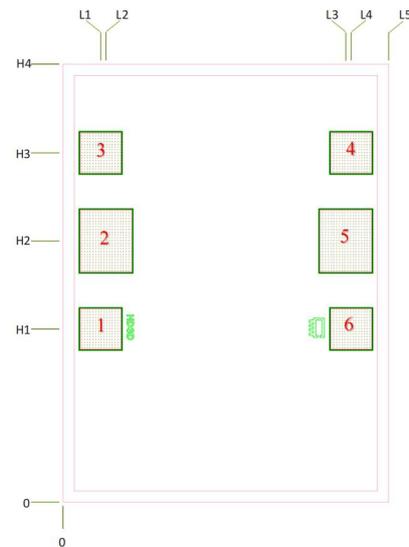
General Description

EQYT-3-24-D is an absorptive Gain Equalizer Die fabricated using highly repetitive GaAs IPD MMIC process incorporating resistors, capacitors and inductors having negative insertion loss slope. EQYT-3-24-D has a nominal attenuation slope of 3.0 dB.

Simplified Schematic and Pad description



Bonding Pad Position



Dimensions in μm , Typical

Pad Number	Function	Description
2	RF-IN	RF-Input pad
5	RF-OUT	RF-Output pad
1,3,4,6	GND	Ground

L1	L2	L3	L4	L5	H1	H2	H3	H4	Thickness	Die Size	Bond Pad #1, #3, #4, #6	Bond Pad #2, #5
87	99	651	664	750	401	606	809	1015	100	750x1015	92 X 92	117 X 142

Electrical Specifications¹ at 25°C, 50Ω, unless otherwise noted.

Parameter	Condition (GHz)	Min.	Typ.	Max.	Units
Frequency Range		DC		20	GHz
Insertion Loss	0.01	—	3.8	—	dB
	5	—	3.4	—	
	10	—	2.4	—	
	18	—	1.1	—	
	20	—	0.8	—	
VSWR	0.01 - 5	—	1.01	—	:1
	5 - 10	—	1.08	—	
	10 - 18	—	1.24	—	
	18 - 20	—	1.27	—	

1. Measured on Die using MPI Titan series, 200 μm pitch GSG probe.

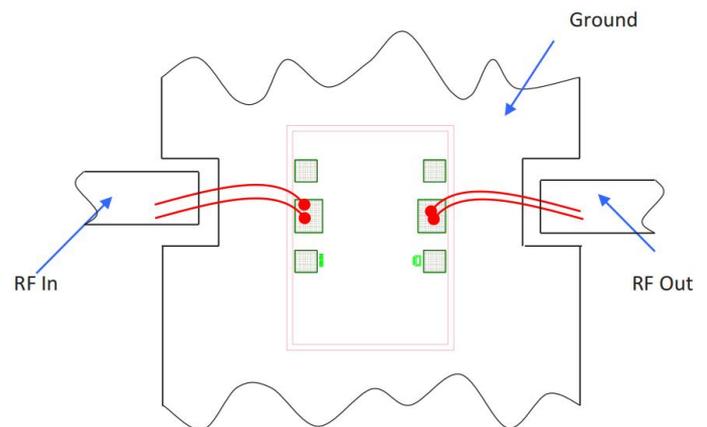
Absolute Maximum Ratings²

Operating Case Temperature	-55°C to 105°C
RF Input Power ³	34 dBm

2. Permanent damage may occur if any of these limits are exceeded.

3. Derates linearly to 32 dBm at 105° C

Assembly Diagram



Assembly and Handling Procedure

1. Storage

Dice should be stored in a dry nitrogen purged desiccators or equivalent.

2. ESD

MMIC GaAs Gain equalizer dice are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic protected material, which should be opened in clean room conditions at an appropriately grounded anti-static workstation. Devices need careful handling using correctly designed collets, vacuum pickup tips or sharp antistatic tweezers to deter ESD damage to dice.

3. Die Attach

The die mounting surface must be clean and flat. Using conductive silver filled epoxy, recommended epoxies are DieMat DM6030HK-PT/H579 or Ablestik 84-1LMISR4. Apply sufficient epoxy to meet required epoxy bond line thickness, epoxy fillet height and epoxy coverage around total die periphery. Parts shall be cured in a nitrogen filled atmosphere per manufacturer's cure condition. It is recommended to use antistatic die pick up tools only.

4. Wire Bonding

Bond pad openings in the surface passivation above the bond pads are provided to allow wire bonding to the dice gold bond pads. Thermosonic bonding is used with minimized ultrasonic content. Bond force, time, ultrasonic power and temperature are all critical parameters. Suggested wire is pure gold, 1 mil diameter. Bonds must be made from the bond pads on the die to the package or substrate. All bond wires should be kept as short as low as reasonable to minimize performance degradation due to undesirable series inductance.